Health informatics—Point-of-care medical device communication

## Part 20701: Service-Oriented Medical Device Exchange Architecture and Protocol Binding

IEEE Engineering in Medicine and Biology Society

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Abstract: Within the context of the ISO/IEEE 11073 family of standards for point-of-care (PoC) medical device communication, an architecture for service-oriented distributed PoC medical devices and medical IT systems is defined. This standard defines a binding of the Participant, Discovery, and Communication Model defined in IEEE Std 11073-10207™ to the profile for transport over Web Services defined in IEEE Std 11073-20702™. Moreover, a binding to Network Time Protocol (NTP) and Differentiated Services (DiffServ) is defined for time synchronization and transport Quality of Service requirements.

**Keywords:** alert systems, BICEPS, DiffServ, IEEE 11073-20701™, ISO/IEEE 11073, MDPWS, medical device communication, NTP, patient, point-of-care, remote control, service-oriented architecture

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